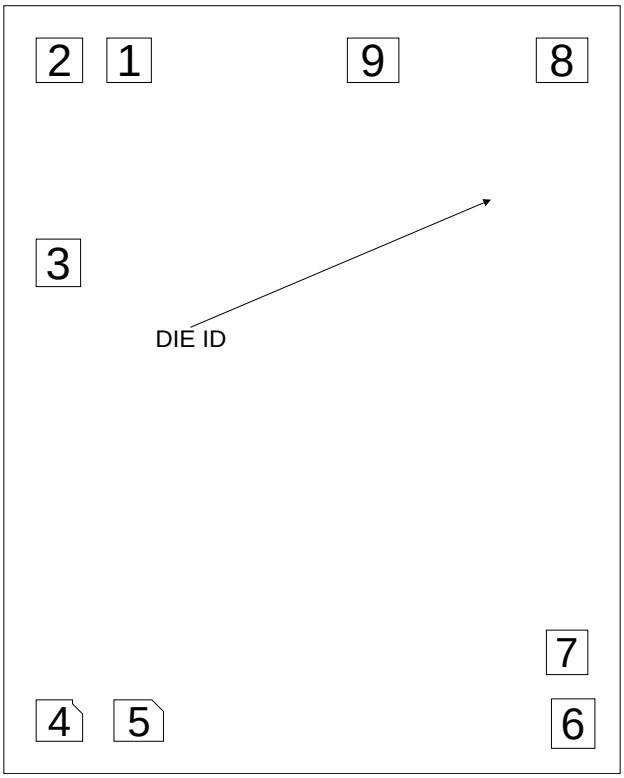
LM118 MDS MCD4070A
OPERATIONAL AMPLIFIERS

FEB 10, 2010

DIE LAYOUT (F-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM118F	Bond Pad Opening Size (min)	104.14µm x 111.76µm
Die Step	F	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1549.4µm x 1930.4µm 61.0mils x 76.0mils	Back Side Connection	Floating or -VCC
Thickness	304.8µm Nominal		
Min Pitch	175.26µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(F-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
BAL/COMP-1	1	-460	828	112	x	112
INPUT -	2	-635	828	117	x	112
INPUT +	3	-638	319	112	x	119
V-	4	-635	-832	117	x	104
BAL/COMP-3	5	-436	-832	124	x	104
NC	6	657	-839	109	x	124
OUTPUT	7	641	-660	104	x	112
V+	8	629	828	130	x	112
COMP-2	9	154	828	130	x	112

Notes

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